

WHAT IS CLAIMED IS:

1. A method of manufacturing a semiconductor device, comprising:
providing liquid resin on a first semiconductor chip having a plurality of pads,
which is mounted on a substrate having wiring patterns;
mounting a second semiconductor chip over the first semiconductor chip
through the liquid resin, in an overlapping manner and separated from the pads; and
hardening the liquid resin to form a spacer between the first semiconductor
chip and the second semiconductor chip, and to fix the first and second semiconductor chips
together.
2. The method of manufacturing a semiconductor device according to claim 1,
further including forming the spacer such that the first semiconductor chip is oriented
generally in parallel with the second semiconductor chip.
3. The method of manufacturing a semiconductor device according to claim 2,
the liquid resin including a plurality of balls, such that the balls are present between the first
and second semiconductor chips.
4. The method of manufacturing a semiconductor device according to claim 3,
the balls being elastic.
5. The method of manufacturing a semiconductor device according to claim 1,
further comprising electrically connecting the pads on the first semiconductor chip and the
wiring patterns with wires, before the mounting of the second semiconductor chip.
6. The method of manufacturing a semiconductor device according to claim 1,
further including forming a dielectric layer on a surface of the second semiconductor chip that
faces the first semiconductor chip.
7. The method of manufacturing a semiconductor device according to claim 1,
further comprising forming a sealing section on the substrate to seal the first and second
semiconductor chips.
8. A semiconductor device fabricated by the method of manufacturing a
semiconductor device according to claim 1.
9. A circuit substrate, comprising:
the semiconductor device according to claim 8.
10. An electronic equipment, comprising:
the semiconductor device according to claim 8.